



SHIN-ETSU X23-7783D Thermal Compound 0.5 Gram Tube

\$3.95

Product Images



Short Description

Shin-Etsu X23 Thermal Compound (Model X23-7783D) - This thermal interface compound is developed by Shin Etsu Chemical Co., Ltd. to meet the current and future requirements of high performance microprocessors. Shin-Etsu MicroSi's X23-7783D product offering utilizes fillers that have a controlled diameter. The smaller diameter filler allows the material to achieve thinner bondlines. For best results, this

material should be used in applications where the hills and valleys of the mating surfaces are minimal.

Description

Shin-Etsu X23 Thermal Compound (Model X23-7783D) - This thermal interface compound is developed by Shin Etsu Chemical Co., Ltd. to meet the current and future requirements of high performance microprocessors. Shin-Etsu MicroSi's X23-7783D product offering utilizes fillers that have a controlled diameter. The smaller diameter filler allows the material to achieve thinner bondlines. For best results, this material should be used in applications where the hills and valleys of the mating surfaces are minimal.

Note: This Item can not be shipped using DHL

Features

- Injector with cap for easy application and storage
- High performance thermal grease. Ideally suited for applications where the mating surfaces have minimal "hills and valleys".
- 0.50gm syringe (comes in 1cc syringe)

Specifications

- Thermal Conductivity: 6.0 (W/m °K)
- Specific Gravity: 2.6
- Electrically non-conductive
- Viscosity: (Pa.s @ 25C) 250
- Storage Conditions 60°F to 85°F (15°C - 29°C)

Additional Information

SKU	X23-7783D-0.5G
Weight	0.1000
TIM Type	Paste

